

INDIUM CORPORATION EXPERT TO PRESENT AT SEMICON SOUTHEAST ASIA

23 April 2016

- Global SMT and Packaging

Indium Corporation's Kenny Chiong, Senior Technical Support Engineer, will present Ultra-low Residue, No-Clean Material for Advanced Packaging Assembly at SEMICON Southeast Asia, on April 26-28 in Penang, Malaysia.

Chiong's presentation will detail how semiconductor-grade, ultra-low residue, no-clean fluxes and solder pastes eliminate the need for multiple cleaning steps in the flip-chip, as well as in system-in-package (SiP) assembly processes. Ultra-low residue no-clean fluxes help to Avoid the Void™ by reducing the flux residue left behind after soldering, thereby decreasing the danger of delamination.

Chiong is based in Singapore and assists customers in the optimization of manufacturing processes, including technical support for Indium Corporation's full suite of products. Prior to joining Indium Corporation, Kenny provided technical support for surface mount technology processes, as well as equipment. Additionally, he also reviewed designs for printed circuit board assembly to maintain quality, delivery, and optimal output for manufacturing standards. Chiong holds a bachelor's degree in mechanical and manufacturing engineering from the Universiti Malaysia Sarawak and has earned his Six Sigma Green Belt.